



## PRODUCT DATA SHEET



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**Datasheet**



**Resources**



**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

## General Description

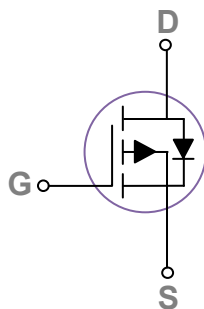
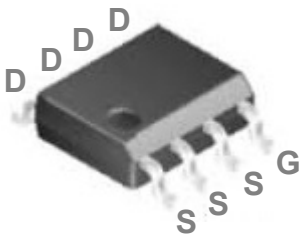
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

|       |       |      |
|-------|-------|------|
| BVDSS | RDSON | ID   |
| -40V  | 15mΩ  | -10A |

## Features

- -40V,-10A,  $R_{DS(ON)} = 15m\Omega @ V_{GS} = -10V$
- Fast switching
- Green Device Available
- Suit for -4.5V Gate Drive Applications

## SOP8 Pin Configuration



## Applications

- MB / VGA / Vcore
- POL Applications
- Load Switch
- LED Application

## Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

| Symbol    | Parameter  | Rating     | Units               |
|-----------|--|------------|---------------------|
| $V_{DS}$  | Drain-Source Voltage                                   | -40        | V                   |
| $V_{GS}$  | Gate-Source Voltage                                    | $\pm 20$   | V                   |
| $I_D$     | Drain Current – Continuous ( $T_c=25^\circ\text{C}$ )  | -10        | A                   |
|           | Drain Current – Continuous ( $T_c=100^\circ\text{C}$ ) | -6.3       | A                   |
| $I_{DM}$  | Drain Current – Pulsed <sup>1</sup>                    | -40        | A                   |
| $P_D$     | Power Dissipation ( $T_c=25^\circ\text{C}$ )           | 4.2        | W                   |
|           | Power Dissipation – Derate above $25^\circ\text{C}$    | 0.034      | W/ $^\circ\text{C}$ |
| $T_{STG}$ | Storage Temperature Range                              | -55 to 150 | $^\circ\text{C}$    |
| $T_J$     | Operating Junction Temperature Range                   | -55 to 125 | $^\circ\text{C}$    |

## Thermal Characteristics

| Symbol          | Parameter                              | Typ. | Max. | Unit                      |
|-----------------|--|------|------|---------------------------|
| $R_{\theta JC}$ | Thermal Resistance Junction to Case    | ---  | 30   | $^\circ\text{C}/\text{W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient | ---  | 60   | $^\circ\text{C}/\text{W}$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

| Symbol     | Parameter                      | Conditions                                      | Min. | Typ. | Max.      | Unit    |
|------------|--------------------------------|---|------|------|-----------|---------|
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}=0V, I_D=-250\mu A$                      | -40  | ---  | ---       | V       |
| $I_{DSS}$  | Drain-Source Leakage Current   | $V_{DS}=-40V, V_{GS}=0V, T_J=25^\circ\text{C}$  | ---  | ---  | -1        | $\mu A$ |
|            |                                | $V_{DS}=-32V, V_{GS}=0V, T_J=125^\circ\text{C}$ | ---  | ---  | -10       | $\mu A$ |
| $I_{GSS}$  | Gate-Source Leakage Current    | $V_{GS}=\pm 20V, V_{DS}=0V$                     | ---  | ---  | $\pm 100$ | nA      |

**On Characteristics**

|              |                                   |                                |      |      |      |           |
|--------------|-----------------------------------|--------------------------------|------|------|------|-----------|
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance | $V_{GS}=-10V, I_D=-10A$        | ---  | 11.5 | 15   | $m\Omega$ |
|              |                                   | $V_{GS}=-4.5V, I_D=-8A$        | ---  | 16   | 22   | $m\Omega$ |
| $V_{GS(th)}$ | Gate Threshold Voltage            | $V_{GS}=V_{DS}, I_D=-250\mu A$ | -1.0 | -1.6 | -2.5 | V         |
| gfs          | Forward Transconductance          | $V_{DS}=-10V, I_D=-10A$        | ---  | 13   | ---  | S         |

**Dynamic and switching Characteristics**

|              |                                    |  |     |      |      |    |
|--------------|------------------------------------|--|-----|------|------|----|
| $Q_g$        | Total Gate Charge <sup>2,3</sup>   | $V_{DS}=-32V, V_{GS}=-4.5V, I_D=-10A$                | --- | 22.2 | 40   | nC |
| $Q_{gs}$     | Gate-Source Charge <sup>2,3</sup>  |  | --- | 8.2  | 16   |    |
| $Q_{gd}$     | Gate-Drain Charge <sup>2,3</sup>   |  | --- | 8.8  | 16   |    |
| $T_{d(on)}$  | Turn-On Delay Time <sup>2,3</sup>  | $V_{DD}=-20V, V_{GS}=-10V, R_G=6\Omega$<br>$I_D=-1A$ | --- | 23   | 40   | ns |
| $T_r$        | Rise Time <sup>2,3</sup>           |  | --- | 10   | 20   |    |
| $T_{d(off)}$ | Turn-Off Delay Time <sup>2,3</sup> |  | --- | 135  | 250  |    |
| $T_f$        | Fall Time <sup>2,3</sup>           |  | --- | 46   | 90   |    |
| $C_{iss}$    | Input Capacitance                  | $V_{DS}=-25V, V_{GS}=0V, F=1\text{MHz}$              | --- | 2757 | 4000 | pF |
| $C_{oss}$    | Output Capacitance                 |  | --- | 240  | 360  |    |
| $C_{rss}$    | Reverse Transfer Capacitance       |  | --- | 137  | 200  |    |

**Drain-Source Diode Characteristics and Maximum Ratings**

| Symbol   | Parameter                 | Conditions                                 | Min. | Typ. | Max. | Unit |
|----------|---------------------------|--|------|------|------|------|
| $I_S$    | Continuous Source Current | $V_G=V_D=0V$ , Force Current               | ---  | ---  | -10  | A    |
| $I_{SM}$ | Pulsed Source Current     |  | ---  | ---  | -20  | A    |
| $V_{SD}$ | Diode Forward Voltage     | $V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$ | ---  | ---  | -1   | V    |

**Note :**

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ .
3. Essentially independent of operating temperature.

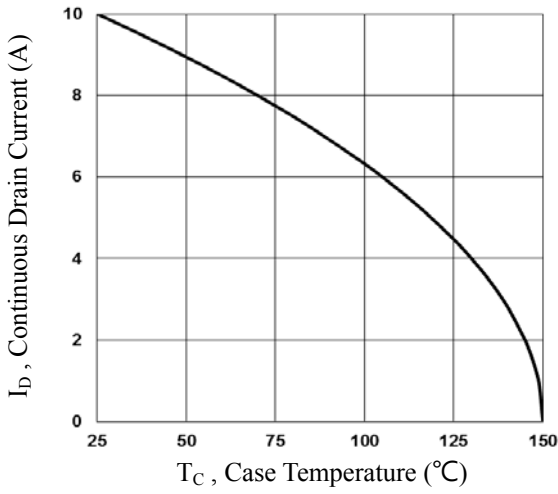


Fig.1 Continuous Drain Current vs. T<sub>c</sub>

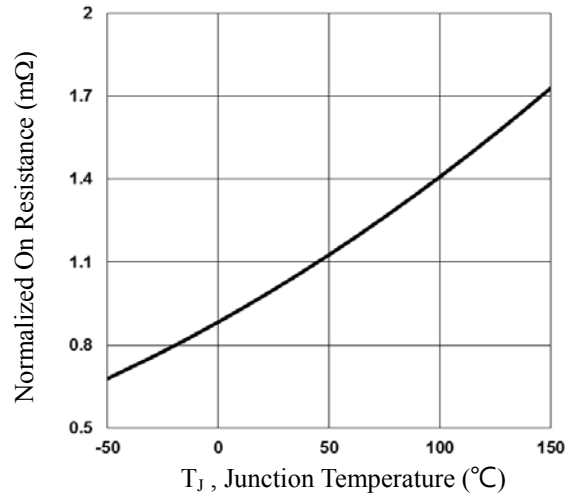


Fig.2 Normalized R<sub>DSon</sub> vs. T<sub>j</sub>

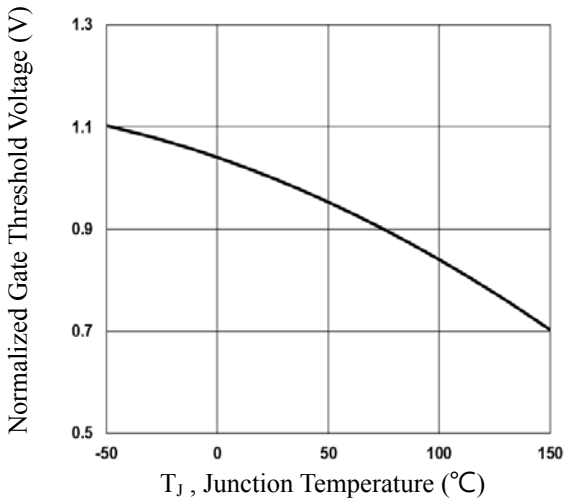


Fig.3 Normalized V<sub>th</sub> vs. T<sub>j</sub>

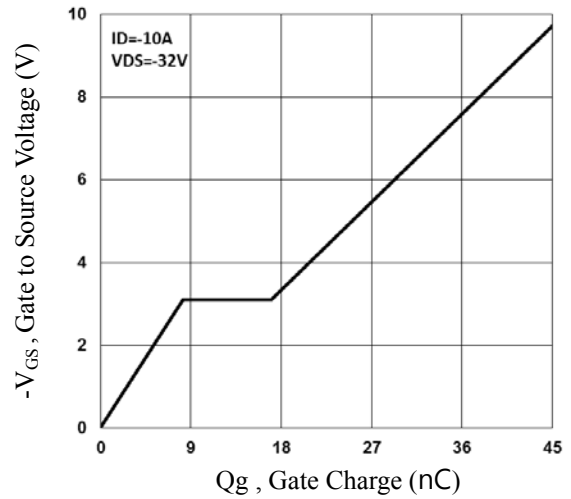


Fig.4 Gate Charge Waveform

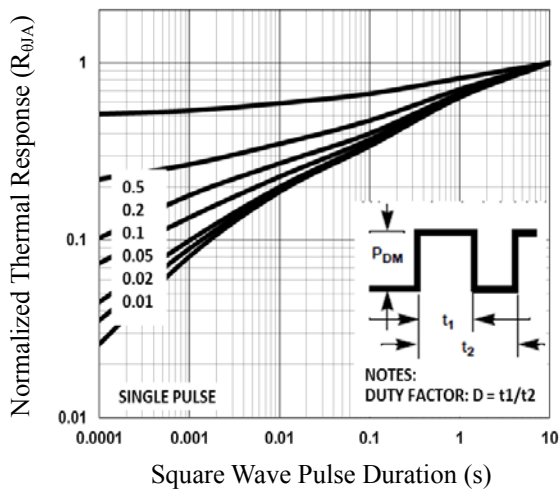


Fig.5 Normalized Transient Impedance

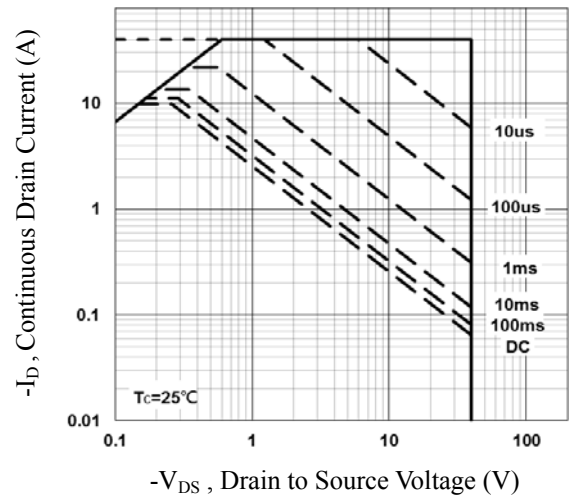


Fig.6 Maximum Safe Operation Area

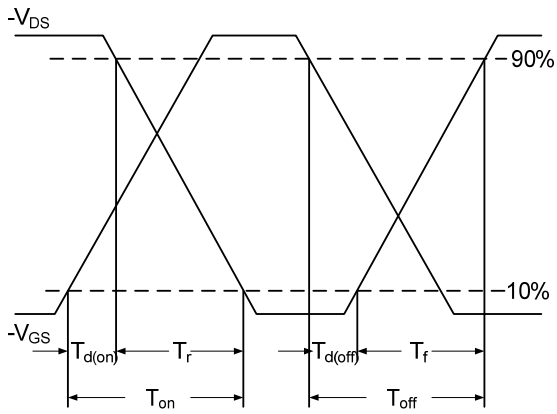


Fig.7 Switching Time Waveform

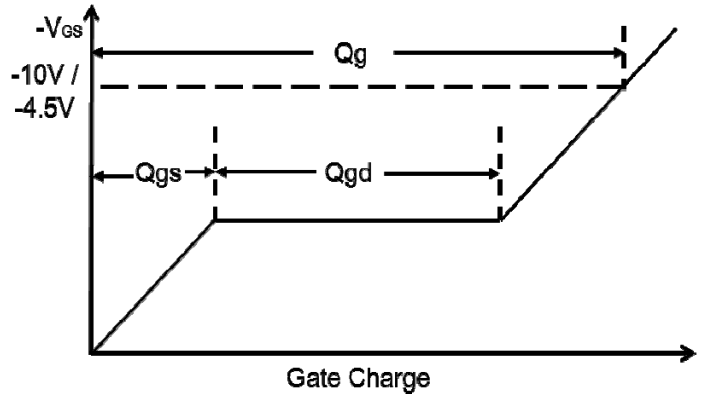
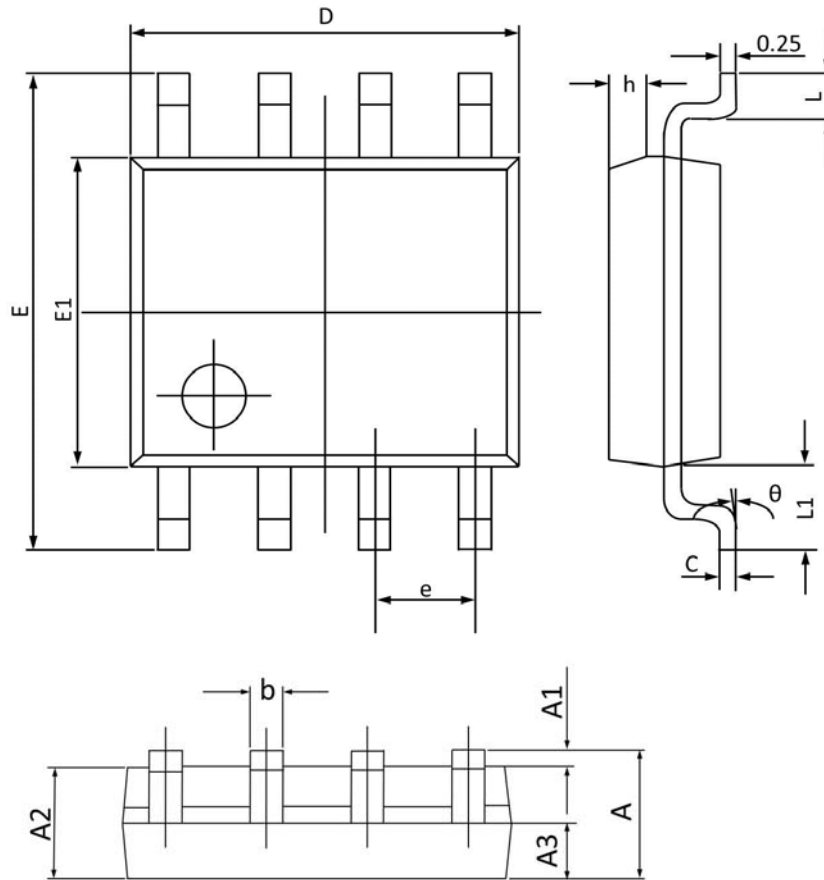


Fig.8 Gate Charge Waveform



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min                       | Max   | Min                  | Max   |
| A      | 1.350                     | 1.750 | 0.053                | 0.068 |
| A1     | 0.100                     | 0.250 | 0.004                | 0.009 |
| A2     | 1.300                     | 1.500 | 0.052                | 0.059 |
| A3     | 0.600                     | 0.700 | 0.024                | 0.027 |
| b      | 0.390                     | 0.480 | 0.016                | 0.018 |
| c      | 0.210                     | 0.260 | 0.009                | 0.010 |
| D      | 4.700                     | 5.100 | 0.186                | 0.200 |
| E      | 5.800                     | 6.200 | 0.229                | 0.244 |
| E1     | 3.700                     | 4.100 | 0.146                | 0.161 |
| e      | 1.270(BSC)                |       | 0.050(BSC)           |       |
| h      | 0.250                     | 0.500 | 0.010                | 0.019 |
| L      | 0.500                     | 0.800 | 0.019                | 0.031 |
| L1     | 1.050(BSC)                |       | 0.041(BSC)           |       |
| θ      | 0°                        | 8°    | 0°                   | 8°    |

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